## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Raj PENDSE

Application No.: 10/081,425

Filed: 22 February 2002

Title: Apparatus and process for precise

encapsulation of flip chip interconnects

Attorney Docket No.: CPAC 1011-2

Examiner: Scott B/ Geyer

Ry. No. 33, 407

Group: 9980

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Sir:

The undersigned, Bill Kennedy, Reg. No. 33,407, attorney of record in this application, hereby grants Annette Maciello and Rayline Petitt of Patent and Trademark Services the power to inspect and make copies of the subject application, including provisional patent application No. 60/272,280 from which this non-provisional application claims priority.

espectfully submitted,

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